

## ALTERNATION HISTORY RECORDS 变更记录

Date 日期	Version 版本	Mark 标记	Page 页码	Description 描述	Drafter 制定者	Approver 审批者
2023-10-04	B		/	First release 首次发行	Doris Chang	/
2025-02-24	B-1	▲	P2	Renewal Permissible Operating Current	Doris Chang	Emily Peng

## 1、产品标识（料号） Product Identification(Part Number)

**NC    0603    -    103    F    3380    F    B**

(1)      (2)      (3)      (4)      (5)      (6)      (7)      (8)

① 类别 Type	
NC	片式 NTC 热敏电阻器 Chip NTC Thermistor

④ 25°C的零功率电阻 Nominal Zero-Power Resistance	
222	2.2kΩ
103	10kΩ
105	1000kΩ

⑥ B 值常数 B Constant	
3380	3380K
3950	3950K
4100	4100K
4750	4750K

② 外形尺寸(mm) External Dimensions (L×W×T)	
0201[0603]	0.60×0.30×0.30
0402[1005]	1.00×0.50×0.50
0603[1608]	1.60×0.80×0.80
0805[2012]	2.00×1.25×0.85

⑤ 电阻值公差 Tolerance of Resistance	
F	±1%
G	±2%
H	±3%
J	±5%

⑦ B 值公差 Tolerance of B Constant	
F	±1%
H	±3%

⑧ B 值计算方式 B constant calculation method	
A	25°C&85°C
B	25°C&50°C

## 2、Overall dimensions (unit: (mm))

Dimensions: See Fig.1 and Table 1.

Recommended PCB pattern for reflow soldering: See Fig.2 and Table 1

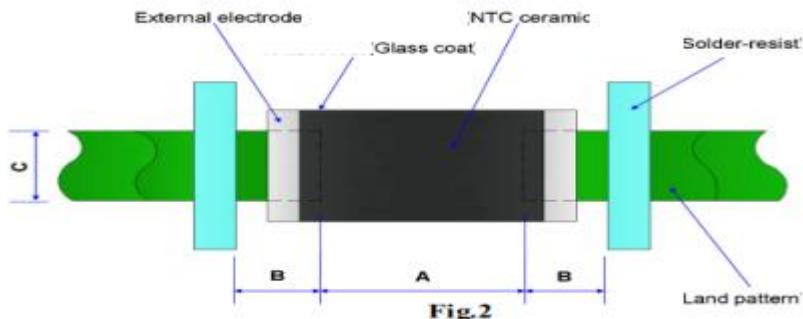
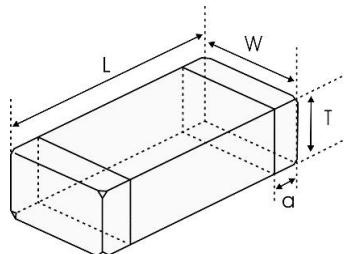


Fig.1

Table 1 unit: inch[mm]

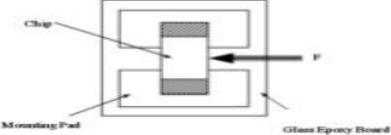
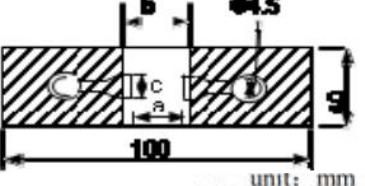
Type	L	W	T	a	A	B	C
0402 [1005]	0.039±0.006 [1.0±0.15]	0.020±0.006 [0.5±0.15]	0.020±0.006 [0.5±0.15]	0.010±0.004 [0.25±0.1]	[0.45-0.55]	[0.4-0.5]	[0.45-0.55]

## 3. Electrical Characteristics

Items	Symbol	Test condition	unit	performance requirement
Nominal Zero-Power Resistance	R <sub>25°C</sub>	At=25±0.05°C P≤0.1mW	KΩ	1000±3%
B Constant	B <sub>25/85</sub>	B value between 25±0.05°C and 85±0.05°C B=Ln (R <sub>i</sub> /R <sub>2</sub> )/(1/T <sub>i</sub> -1/T <sub>2</sub> ); T <sub>1</sub> =(273.15+25)K, T <sub>2</sub> =(273.15+85) K Note:273.15 is the absolute temperature.	K	4750±3%
Dissipation Factor	δ	The required power which makes the NTC thermistor body temperature raise 1°C through self-heated, normally expressed in milliwatts per degree Celsius (mW/°C).	mW/°C	≈1.0
Thermal Time Constant	τ	The total time for the temperature of the thermistor to change by 63.2% of the difference from ambient temperature T <sub>0</sub> (°C) to T <sub>1</sub> (°C) by the drastic change of the power applied to thermistor from Non-zero Power to Zero-Power state, normally expressed in second(S).	sec	<3S
Rated Electric Power	P	The necessary electric power makes thermistor's temperature rise 100°C by self-heating at ambient temperature 25°C.	mW	100
Permissible Operating Current	I	The current that keep body temperature of chip NTC on the PC board in still air rising 1°C by self-heating.	mA	0.03 △
Operating ambient temperature	/	Temperature range under specified conditions of use	°C	-40°C ~+125°C

Notes: When measured at 25°C in still air, as a single unit without mounting.

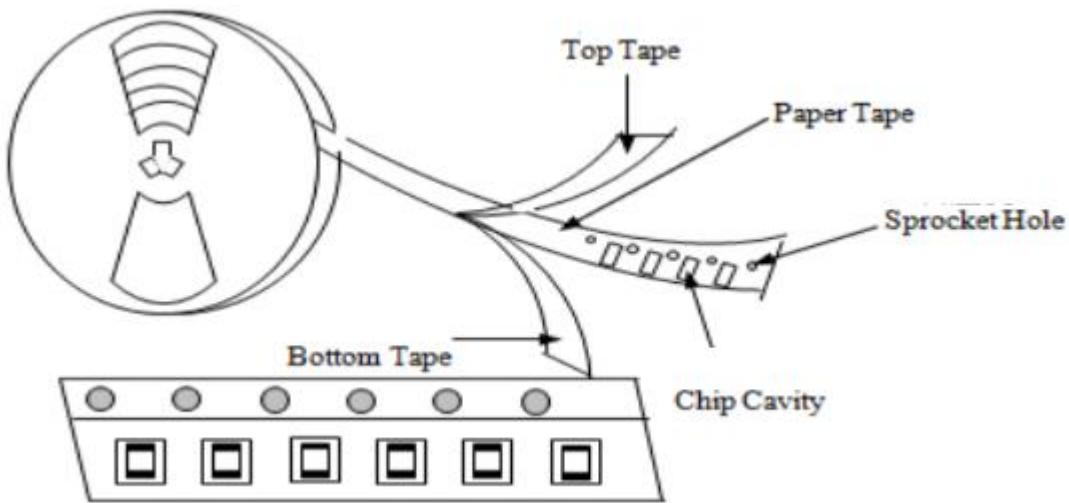
#### 4. Reliability Test (一)

Item	Standard	Test Method and Remarks	Requirements																				
Terminal Strength	IEC 60068-2-21	<p>1.Solder the chip to the testing jig (glass epoxy board shown in the right) using eutectic solder. Then apply a force in the direction of the arrow.</p> <p>2.Apply a force of 5N</p> <p>3.Duration: <math>10 \pm 1</math>S</p>	<p>No removal or split of the termination or other defects shall occur.</p> 																				
Resistance to Flexure	IEC 60068-2-21	<p>1.Solder the chip to the test jig (glass epoxy board shown in the right) using a eutectic solder. Then apply a force in the direction shown as follow;</p> <p>2 Flexure:Pressurizing Speed : <math>&lt; 0.5</math>mm/s,</p> <p>3.Duration: 10s</p>	<p>1.No visible damage.</p> <p>2. <math> \Delta R_{25}/R_{25}  \leq 2\%</math></p>  <table border="1" data-bbox="975 826 1356 1064"> <thead> <tr> <th>Type</th><th>a</th><th>b</th><th>c</th></tr> </thead> <tbody> <tr> <td>0201</td><td>0.25</td><td>0.3</td><td>0.3</td></tr> <tr> <td>0402</td><td>0.4</td><td>1.5</td><td>0.5</td></tr> <tr> <td>0603</td><td>1.0</td><td>3.0</td><td>1.2</td></tr> <tr> <td>0805</td><td>1.2</td><td>4.0</td><td>1.65</td></tr> </tbody> </table>	Type	a	b	c	0201	0.25	0.3	0.3	0402	0.4	1.5	0.5	0603	1.0	3.0	1.2	0805	1.2	4.0	1.65
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0603	1.0	3.0	1.2																				
0805	1.2	4.0	1.65																				
Vibration	IEC 60068-2-80	<p>1.Solder the chip to the testing jig (glass epoxy board shown in the left) using eutectic solder.</p> <p>2.The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz.</p> <p>3.The frequency ranges from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).。</p>	No visible damage.																				
Dropping	IEC 60068-2-32	Drop a chip 10 times on a concrete floor from a height of 1 meter..	No visible damage.																				

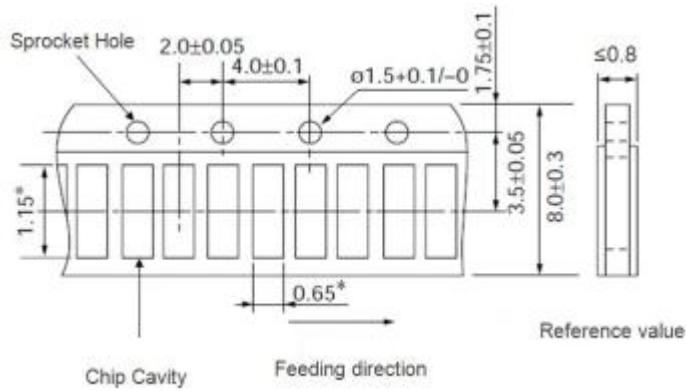
Solderability	IEC 60068-2-58	1. Solder temperature: $245\pm5^{\circ}\text{C}$ . 2. Duration: $3\pm0.3\text{s.}$ 3. Solder: Sn/3.0Ag/0.5Cu. 4. Flux(weight ratio): 25% Rosin and 75% ethanol in weight.	1. No visible damage; 2. Wetting shall exceed 95% coverage. .															
Resistance to Soldering Heat	IEC 60068-2-58	1. Solder temperature: $260\pm5^{\circ}\text{C}$ . 2. Duration: $10\pm1\text{s.}$ 3. Solder: Sn/3.0Ag/0.5Cu. 4. Flux(weight ratio): 25% Rosin and 75% ethanol in weight. 5. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$															
Temperature cycling	IEC 60068-2-14	1. 5 cycles of following sequence without loading. <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Step</th> <th>Temperature</th> <th>Time</th> </tr> </thead> <tbody> <tr> <td>1</td> <td><math>-40\pm 5^{\circ}\text{C}</math></td> <td><math>30\pm 3\text{min}</math></td> </tr> <tr> <td>2</td> <td><math>25\pm 2^{\circ}\text{C}</math></td> <td><math>5\pm 3\text{min}</math></td> </tr> <tr> <td>3</td> <td><math>125\pm 5^{\circ}\text{C}</math></td> <td><math>30\pm 3\text{min}</math></td> </tr> <tr> <td>4</td> <td><math>25\pm 2^{\circ}\text{C}</math></td> <td><math>5\pm 3\text{min}</math></td> </tr> </tbody> </table> 2. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	Step	Temperature	Time	1	$-40\pm 5^{\circ}\text{C}$	$30\pm 3\text{min}$	2	$25\pm 2^{\circ}\text{C}$	$5\pm 3\text{min}$	3	$125\pm 5^{\circ}\text{C}$	$30\pm 3\text{min}$	4	$25\pm 2^{\circ}\text{C}$	$5\pm 3\text{min}$	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$
Step	Temperature	Time																
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3	$125\pm 5^{\circ}\text{C}$	$30\pm 3\text{min}$																
4	$25\pm 2^{\circ}\text{C}$	$5\pm 3\text{min}$																
Resistance to dry heat	IEC 60068-2-2	1. $125\pm 5^{\circ}\text{C}$ in air, for $1000\pm 24$ hours without loading. 2. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$															
Resistance to cold	IEC 60068-2-1	1. $-40\pm 3^{\circ}\text{C}$ in air, for $1000\pm 24$ hours without loading. 2. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$															
Resistance to damp heat	IEC 60068-2-78	1. $60\pm 2^{\circ}\text{C}$ , 90~95%RH in air, for $1000\pm 24$ hours without loading. 2. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$															
Resistance to high temperature load	IEC 60539-15. 25. 4	1. $85\pm 2^{\circ}\text{C}$ in air with permissive operating current for $1000\pm 48$ hours 2. The chip shall be stabilized at normal condition for 1~2 hours before measuring.	1. No visible damage; 2. $ \Delta R_{25}/R_{25}  \leq 2\%$ 3. $ \Delta B/B  \leq 1\%$															

## 5. Taping

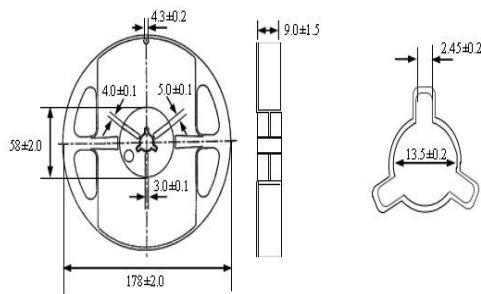
### 5.1 Taping Drawings



### 5.2 Paper Tape Dimensions (0402series) (Unit: mm)



### 5.3 Reel Dimensions (Unit: mm) /Quantity per Reel: (10K)



## 6. Storage

- . **Storage Conditions**
  - a. Storage Temperature:  $-10^{\circ}\text{C} \sim 40^{\circ}\text{C}$
  - b. Relative Humidity:  $\leq 75\%$ RH
  - c. Keep away from corrosive atmosphere and sunlight.
- . **Period of Storage: 6 Months after delivery**

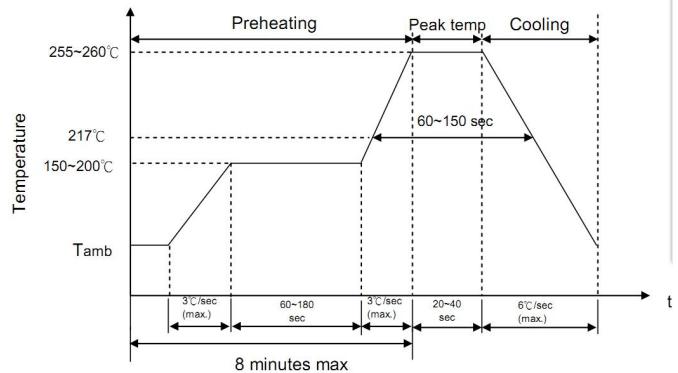
## 7. Notes & Warnings

- . The NC series thermistors shall not be operated and stored under the following environmental condition:
  - (1) Corrosive or deoxidized atmospheres  
(such as chlorine, sulfurated hydrogen, ammonia, sulfuric acid, nitric oxide and so on)
  - (2) Volatile or inflammable atmospheres
  - (3) Dusty condition
  - (4) Excessively high or low pressure condition
  - (5) Humid site
  - (6) Places with brine, oil, chemical liquid or organic solvent
  - (7) Intense vibration
  - (8) Places with analogously deleterious conditions

## 8. Recommended Soldering Technologies

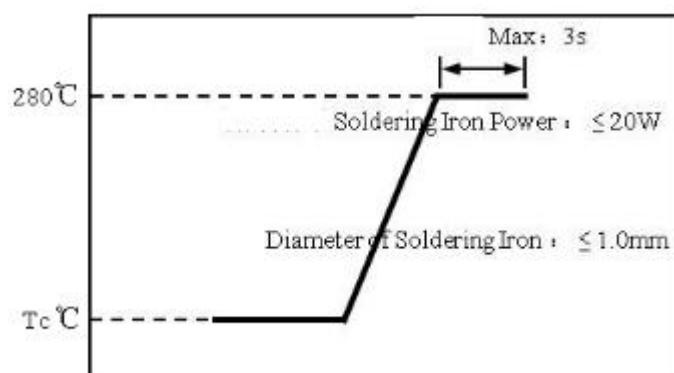
### 8.1 Re-flowing Profile

- $1 \sim 2^{\circ}\text{C/sec}$ . Ramp.
- Pre-heating:  $150 \sim 170^{\circ}\text{C}/90 \pm 30 \text{ sec}$ .
- Time above  $240^{\circ}\text{C}$ :  $20 \sim 40 \text{ sec}$
- Peak temperature:  $260^{\circ}\text{C}$  Max. /10 sec.
- Solder paste: 96.5Sn/3.0Ag/0.5Cu
- Max. 2 times for re-flowing.



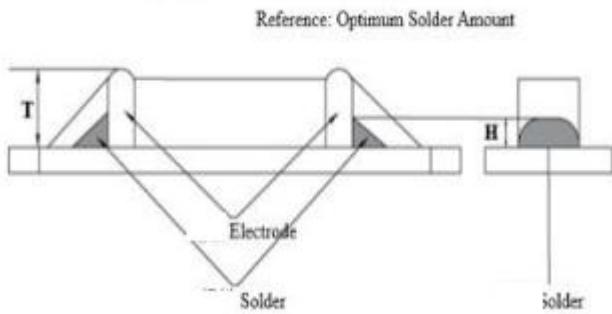
### 8.2 Iron Soldering Profile

- Iron soldering power: Max.20W
- Pre-heating:  $150^{\circ}\text{C}/60\text{sec}$ .
- Soldering Tip temperature:  $280^{\circ}\text{C}$ Max.
- Soldering time: 3 sec Max.
- Solder paste: 96.5wt%Sn/3.0wt%Ag/0.5wt%Cu
- Max.1 times for iron soldering



## 8.3 Printing Conditions of Solder Paste

- The amount of solder is critical . Standard height of fillet is shown in the table below.
- Too much solder may cause mechanical stress , resulting in cracking , mechanical and / or electronic damage.
- 



Type	Solder Paste Thickness	H
0201	100µm	$1/3T \leq H \leq T$
0402	150µm	$1/3T \leq H \leq T$
0603, QN0805	200µm	$0.2mm \leq H \leq T$

### • After Soldering

- For removing the flux after soldering, observe the following points in order to avoid deterioration of the characteristics or any change of the external electrodes quality.
  - 1)Please keep mounted parts and a substrate from an occurrence of resonance in ultrasonic cleaning.
  - 2)Please do not clean the products in the case of using a non-wash-type flux

**Appose: R-T table**

R25 = 1000 KOhm ± 3%

B25/85= 4750 K ± 3%

Temp. (°C)	R_Min (Kohm)	R_Cent (Kohm)	R_Max (Kohm)	Res TOL.	Temp. TOL.(°C)
-40	59,889.859	70,139.129	82,068.482	17.01%	2.03
-39	55,462.936	64,800.518	75,642.010	16.73%	2.02
-38	51,386.584	59,896.303	69,752.414	16.46%	2.00
-37	47,631.431	55,389.142	64,352.378	16.18%	1.98
-36	44,170.684	51,245.054	59,398.945	15.91%	1.96
-35	40,979.892	47,433.102	54,853.102	15.64%	1.94
-34	38,036.734	43,925.111	50,679.402	15.38%	1.92
-33	35,320.824	40,695.413	46,845.626	15.11%	1.91
-32	32,813.542	37,720.612	43,322.481	14.85%	1.89
-31	30,497.866	34,979.378	40,083.318	14.59%	1.87
-30	28,358.238	32,452.253	37,103.889	14.33%	1.85
-29	26,380.428	30,121.486	34,362.117	14.08%	1.83
-28	24,551.415	27,970.870	31,837.897	13.83%	1.81
-27	22,859.283	25,985.606	29,512.912	13.57%	1.79
-26	21,293.121	24,152.176	27,370.465	13.33%	1.77
-25	19,842.934	22,458.225	25,395.333	13.08%	1.75
-24	18,499.566	20,892.456	23,573.627	12.83%	1.73
-23	17,254.622	19,444.539	21,892.673	12.59%	1.71
-22	16,100.403	18,105.019	20,340.901	12.35%	1.69
-21	15,029.848	16,865.244	18,907.741	12.11%	1.67
-20	14,036.476	15,717.291	17,583.537	11.87%	1.65
-19	13,114.337	14,653.900	16,359.463	11.64%	1.63
-18	12,257.967	13,668.418	15,227.445	11.41%	1.61
-17	11,462.344	12,754.748	14,180.099	11.18%	1.58
-16	10,722.855	11,907.294	13,210.665	10.95%	1.56
-15	10,035.254	11,120.924	12,312.956	10.72%	1.54
-14	9,395.640	10,390.926	11,481.301	10.49%	1.52
-13	8,800.419	9,712.973	10,710.506	10.27%	1.50
-12	8,246.286	9,083.091	9,995.808	10.05%	1.48
-11	7,730.196	8,497.627	9,332.840	9.83%	1.45
-10	7,249.342	7,953.223	8,717.594	9.61%	1.43
-9	6,801.139	7,446.788	8,146.392	9.39%	1.41
-8	6,383.204	6,975.482	7,615.855	9.18%	1.39
-7	5,993.337	6,536.687	7,122.880	8.97%	1.36
-6	5,629.509	6,127.994	6,664.615	8.76%	1.34
-5	5,289.848	5,747.184	6,238.439	8.55%	1.32
-4	4,972.624	5,392.211	5,841.940	8.34%	1.30
-3	4,676.240	5,061.190	5,472.899	8.13%	1.27
-2	4,399.219	4,752.380	5,129.272	7.93%	1.25
-1	4,140.197	4,464.178	4,809.179	7.73%	1.23
0	3,897.911	4,195.101	4,510.886	7.53%	1.20
1	3,671.193	3,943.782	4,232.797	7.33%	1.18

Temp. (°C)	R_Min (Kohm)	R_Cent (Kohm)	R_Max (Kohm)	Res TOL.	Temp. TOL.(°C)	
2	3,458.963	3,708.957	3,973.439	7.13%	1.15	
3	3,260.221	3,489.458	3,731.453	6.94%	1.13	
4	3,074.038	3,284.206	3,505.586	6.74%	1.11	
5	2,899.557	3,092.203	3,294.680	6.55%	1.08	
6	2,735.982	2,912.524	3,097.668	6.36%	1.06	
7	2,582.574	2,744.315	2,913.562	6.17%	1.03	
8	2,438.648	2,586.784	2,741.450	5.98%	1.01	
9	2,303.570	2,439.199	2,580.488	5.79%	0.98	
10	2,176.750	2,300.878	2,429.896	5.61%	0.96	
11	2,057.640	2,171.194	2,288.953	5.42%	0.93	
12	1,945.732	2,049.562	2,156.990	5.24%	0.91	
13	1,840.552	1,935.440	2,033.389	5.06%	0.88	
14	1,741.662	1,828.326	1,917.575	4.88%	0.86	
15	1,648.652	1,727.753	1,809.020	4.70%	0.83	
16	1,561.142	1,633.287	1,707.229	4.53%	0.81	
17	1,478.780	1,544.527	1,611.746	4.35%	0.78	
18	1,401.234	1,461.098	1,522.148	4.18%	0.75	
19	1,328.199	1,382.652	1,438.042	4.01%	0.73	
20	1,259.390	1,308.866	1,359.062	3.84%	0.70	
21	1,194.538	1,239.439	1,284.870	3.67%	0.67	
22	1,133.398	1,174.091	1,215.150	3.50%	0.65	
23	1,075.736	1,112.560	1,149.610	3.33%	0.62	
24	1,021.337	1,054.606	1,087.978	3.16%	0.59	
25	970.000	1,000.000	1,030.000	3.00%	0.57	
26	918.619	948.533	978.538	3.16%	0.60	
27	870.252	900.007	929.942	3.33%	0.64	
28	824.705	854.240	884.035	3.49%	0.67	
29	781.801	811.060	840.656	3.65%	0.71	
30	741.372	770.308	799.653	3.81%	0.74	
31	703.262	731.835	760.883	3.97%	0.78	
32	667.327	695.501	724.212	4.13%	0.81	
33	633.431	661.177	689.518	4.29%	0.85	
34	601.448	628.741	656.682	4.44%	0.89	
35	571.260	598.080	625.596	4.60%	0.93	
36	542.758	569.088	596.157	4.76%	0.96	
37	515.838	541.664	568.271	4.91%	1.00	
38	490.405	515.717	541.846	5.07%	1.04	
39	466.369	491.159	516.800	5.22%	1.08	
40	443.646	467.908	493.052	5.37%	1.11	
41	422.158	445.889	470.530	5.53%	1.15	
42	401.831	425.030	449.163	5.68%	1.19	
43	382.597	405.263	428.887	5.83%	1.23	
44	364.391	386.527	409.639	5.98%	1.27	

Temp. (°C)	R_Min (Kohm)	R_Cent (Kohm)	R_Max (Kohm)	Res TOL.	Temp. TOL.(°C)	
45	347.152	368.762	391.364	6.13%	1.31	
46	330.826	351.913	374.007	6.28%	1.35	
47	315.359	335.928	357.516	6.43%	1.39	
48	300.701	320.758	341.845	6.57%	1.43	
49	286.805	306.358	326.948	6.72%	1.47	
50	273.629	292.684	312.784	6.87%	1.51	
51	261.132	279.697	299.312	7.01%	1.56	
52	249.275	267.358	286.495	7.16%	1.60	
53	238.021	255.632	274.299	7.30%	1.64	
54	227.338	244.486	262.690	7.45%	1.68	
55	217.194	233.887	251.636	7.59%	1.72	
56	207.558	223.806	241.109	7.73%	1.77	
57	198.403	214.215	231.080	7.87%	1.81	
58	189.702	205.089	221.524	8.01%	1.85	
59	181.430	196.401	212.416	8.15%	1.90	
60	173.565	188.129	203.732	8.29%	1.94	
61	166.084	180.251	195.452	8.43%	1.99	
62	158.966	172.747	187.553	8.57%	2.03	
63	152.192	165.595	180.017	8.71%	2.07	
64	145.744	158.779	172.825	8.85%	2.12	
65	139.604	152.281	165.960	8.98%	2.17	
66	133.756	146.084	159.405	9.12%	2.21	
67	128.185	140.174	153.145	9.25%	2.26	
68	122.877	134.534	147.165	9.39%	2.30	
69	117.817	129.152	141.451	9.52%	2.35	
70	112.993	124.015	135.990	9.66%	2.40	
71	108.392	119.110	130.769	9.79%	2.44	
72	104.004	114.425	125.777	9.92%	2.49	
73	99.817	109.950	121.003	10.05%	2.54	
74	95.821	105.674	116.436	10.18%	2.59	
75	92.006	101.588	112.066	10.31%	2.63	
76	88.364	97.681	107.883	10.44%	2.68	
77	84.886	93.946	103.879	10.57%	2.73	
78	81.563	90.374	100.046	10.70%	2.78	
79	78.388	86.956	96.374	10.83%	2.83	
80	75.354	83.686	92.857	10.96%	2.88	
81	72.453	80.557	89.486	11.08%	2.93	
82	69.680	77.561	86.257	11.21%	2.98	
83	67.027	74.693	83.161	11.34%	3.03	
84	64.489	71.946	80.192	11.46%	3.08	
85	62.061	69.315	77.346	11.59%	3.13	
86	59.738	66.793	74.616	11.71%	3.18	
87	57.513	64.377	71.996	11.83%	3.23	

Temp. (°C)	R_Min (Kohm)	R_Cent (Kohm)	R_Max (Kohm)	Res TOL.	Temp. TOL.(°C)	
88	55.383	62.061	69.482	11.96%	3.28	
89	53.343	59.841	67.070	12.08%	3.33	
90	51.390	57.712	64.754	12.20%	3.39	
91	49.517	55.670	62.530	12.32%	3.44	
92	47.723	53.710	60.394	12.44%	3.49	
93	46.004	51.830	58.342	12.56%	3.54	
94	44.355	50.026	56.371	12.68%	3.60	
95	42.774	48.294	54.477	12.80%	3.65	
96	41.258	46.631	52.656	12.92%	3.71	
97	39.803	45.034	50.906	13.04%	3.76	
98	38.407	43.500	49.223	13.16%	3.81	
99	37.067	42.026	47.604	13.27%	3.87	
100	35.781	40.609	46.047	13.39%	3.92	
101	34.547	39.248	44.550	13.51%	3.98	
102	33.361	37.940	43.108	13.62%	4.03	
103	32.222	36.682	41.721	13.74%	4.09	
104	31.128	35.472	40.385	13.85%	4.15	
105	30.076	34.308	39.099	13.97%	4.20	
106	29.066	33.188	37.861	14.08%	4.26	
107	28.095	32.111	36.668	14.19%	4.32	
108	27.161	31.074	35.519	14.31%	4.37	
109	26.263	30.076	34.412	14.42%	4.43	
110	25.399	29.115	33.345	14.53%	4.49	
111	24.568	28.190	32.317	14.64%	4.55	
112	23.768	27.299	31.325	14.75%	4.60	
113	22.999	26.440	30.369	14.86%	4.66	
114	22.258	25.613	29.447	14.97%	4.72	
115	21.545	24.816	28.558	15.08%	4.78	
116	20.858	24.048	27.700	15.19%	4.84	
117	20.197	23.307	26.872	15.30%	4.90	
118	19.560	22.593	26.073	15.40%	4.96	
119	18.946	21.905	25.302	15.51%	5.02	
120	18.355	21.241	24.558	15.62%	5.08	
121	17.785	20.600	23.839	15.72%	5.14	
122	17.236	19.982	23.145	15.83%	5.20	
123	16.706	19.385	22.474	15.93%	5.26	
124	16.195	18.810	21.827	16.04%	5.32	
125	15.703	18.254	21.201	16.14%	5.39	